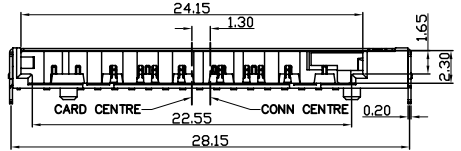
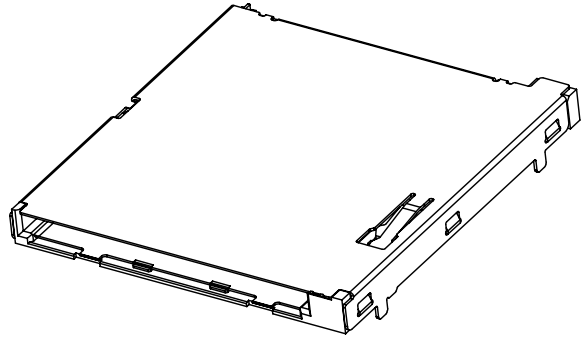


RECOMMENDED PCB LAYOUT
(ALL TOLERANCE ARE ±0.05)

- PAD AREA
- NO TRACE,NO TEST POINT, NO VIA HOLE.NO GROUND AREA



- NOTES :
- MATERIAL :
 - HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
 - SHELL:STAINLESS STEEL SUS304.
 - CONTACT:COPPER ALLOY C5210.
 - FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u"MIN ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN NICKEL PLATING OVERALL. Au 1u"MIN ON SOLDERTAIL AREA.
 - ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

WITHOUT CARD		CARD INSERTED:LOCK	
C/D #12	VSS1 #11	C/D #12	VSS1 #11


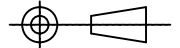
- PART.NO.: TW58-AP401-**-**
- 42: 功能区镀金1U",锡脚镀雾纯锡至少100U"
 - 43: 功能区镀金3U",锡脚镀雾纯锡至少100U"
 - 44: 功能区镀金5U",锡脚镀雾纯锡至少100U"
 - 45: 功能区镀金10U",锡脚镀雾纯锡至少100U"
 - 46: 功能区镀金15U",锡脚镀雾纯锡至少100U"
 - 47: 功能区镀金30U",锡脚镀雾纯锡至少100U"

GENERAL TOLERANCE	DWG.NO.	TW58-AP401-00	PART.NO.	TW58-AP401-**-**	DRAWN	L.M.J 2015.07.01
x.±0.50	REV.	A	TITLE	SD4.0 Push H2.90 CONN	CHECKED	
.x±0.25	SIZE		SHEET	1 OF 3	APPROVED	
.xx±0.15	A4					

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			

Pin Define

Connector PinNo.	Specifications		SD Mode			UHS-II Mode			MMC		
	SD4.0 PinNo.	MMC PinNo.	Name	Type	Description	Name	Type	Description	Name	Type	Description
P1			WP			WP					
P2	P8		DAT1	I/O/PP	Data Line[Bit 1]	RCLK-	I				
P3	P7	P7	DAT0	I/O/PP	Data Line[Bit 0]	RCLK+	I		DAT	I/O/PP	Data
P4	P17		—		Not Used(Connected to ground)	VSS5	S	Supply voltage ground			
P5	P6	P6	VSS2	S	Supply voltage ground	VSS2	S	Supply voltage ground	VSS	S	Supply voltage ground
P6	P16		—		Not Used	D1+	LVDS				
P7	P5	P5	CLK	I	Clock	—		Not Used	CLK	I	Clock
P8	P15		—		Not Used	D1-	LVDS				
P9	P4	P4	VDD	S	Supply voltage	VDD1	S	Supply voltage(3.3V)	VDD	S	Supply voltage
P10	P14		—		Not Used	VDD2	S	Supply voltage(1.8V)			
P11	P3	P3	VSS1	S	Supply voltage ground	VSS1	S	Supply voltage ground	VSS	S	Supply voltage ground
P12			CD			CD					
P13	P13		—		Not Used(Connected to ground)	VSS4	S	Supply voltage ground			
P14	P2	P2	CMD	PP	Command/Response	—		Not Used	CMD	I/O/PP/OD	Command/Reserved
P15	P12		—		Not Used	D0-	LVDS				
P16	P1	P1	CD/DAT3	I/O/PP	Card Detect/ Data Line[Bit 3]	—		Not Used	RSV	NC	Reserved for future use
P17	P11		—		Not Used	D0+	LVDS				
P18	P9		DAT2	I/O/PP	Data Line[Bit 2]	—					
P19	P10		—		Not Used(Connected to ground)	VSS3	S	Supply voltage ground			
P20			GND			GND			GND		
P21			GND			GND			GND		
P22			GND			GND			GND		
P23			GND			GND			GND		
P24			GND			GND			GND		

GENERAL TOLERANCE	DWG.NO.	TW58-AP401-00	PART.NO.	TW58-AP401-**	DRAWN	L.M.J 2015.07.01	UNIT	mm	SCALE	1:1
.x±0.50	REV.	A	TITLE	SD4.0 Push H2.90 CONN	CHECKED		 OLN 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	SIZE		SHEET	2 OF 3	APPROVED					
.xx±0.15	A4									

东莞市欧联电子科技有限公司

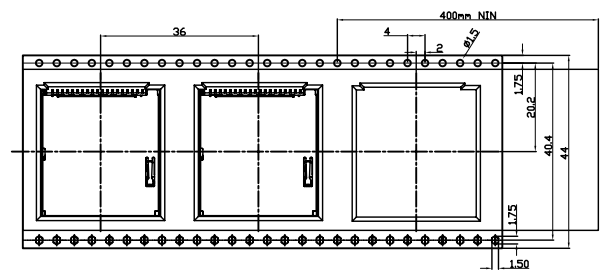
包装作业规范

品名	SD4.0 Push沉板2.0 CONN
料號	TW55-AP401-**

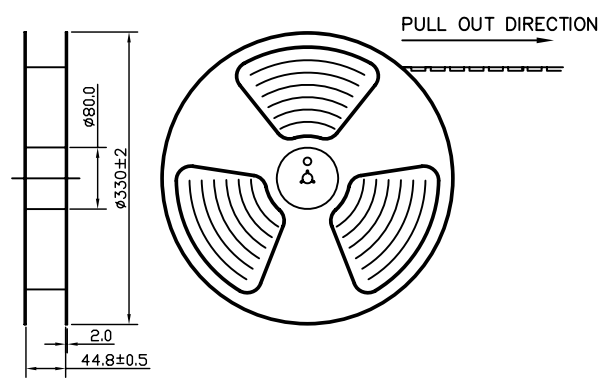
REEL盤料號	W06-0009
紙箱料號	W01-0006

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

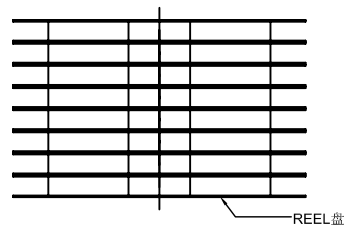
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
 - 2) 包装时,如图所示.
 - 3) 一个REEL包装盘放置300个成品.



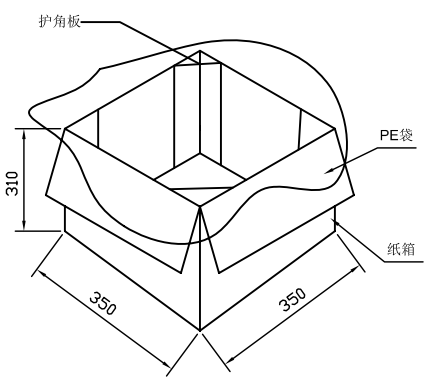
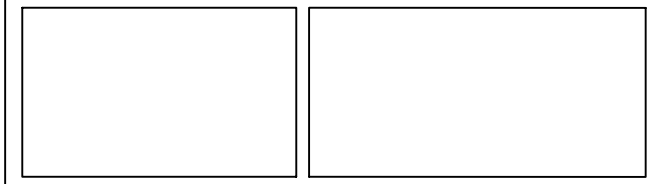
- 二.
- 1) 装盘前先把前面空10pcs产品,然后再开始装盘,尾端也需空11pcs产品,自粘带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装6盘REEL包装盘.
 - 2) 每箱放置1800PCS的成品.



- 四.
- 1) 用TAPE将纸箱封实.



备注 (REMARK)

1. 若有未装满之零数箱,必须以缓冲材塞满.

GENERAL TOLERANCE	DWG.NO.	PART.NO.	DRAWN
x. ± 0.50	TW58-AP401-00	TW58-AP401-**	L.M.J 2015.07.01
x. ± 0.25	REV.	TITLE	CHECKED
.xx ± 0.15	A	SD4.0 Push H2.90 CONN	
	SIZE	SHEET	APPROVED
	A4	3 OF 3	

UNIT	mm	SCALE	1:1
 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			